L	Hits	Search Text	DB	Time stamp
Number 162	4	anneal\$3 SAME copper same chemical adi	UCDAM.	2003/07/11
162	•	anneal\$3 SAME copper same chemical adj polish	USPAT; US-PGPUB;	16:52
			EPO; JPO; DERWENT	
168	366	anneal\$3 same polish\$3 same copper	USPAT;	2003/07/11
		The state of the s	US-PGPUB;	16:56
			EPO; JPO;	
174	9	1, 140	DERWENT	(27 (27
174	9	anneal\$3 same polish\$3 same copper same section	USPAT; US-PGPUB;	2003/07/11
		Section	EPO; JPO;	10:54
			DERWENT	
180	3	I manufication from Francisco Coppor Street	USPAT;	2003/07/11
		housing	US-PGPUB;	16:59
			EPO; JPO; DERWENT	
186	119	anneal\$3 same chemical adj polish\$3	USPAT;	2003/07/11
			US-PGPUB;	17:03
			EPO; JPO;	
192	24	anneal\$3 same chemical adj polish\$3 AND	DERWENT USPAT;	2003/07/11
	"	copper	US-PGPUB;	17:16
		.**	EPO; JPO;	
1.00			DERWENT	
198	4	anneal\$3 same copper adj plating same chemical adj polish\$3	USPAT;	2003/07/11
		Chemical adj polishas	US-PGPUB; EPO; JPO;	17:49
			DERWENT	
204	14802	I The major to the control of the co	USPAT;	2003/07/11
		anneal\$3 and electrolytic or chemical adj	US-PGPUB;	17:50
		polishing	EPO; JPO; DERWENT	
210	6564	(copper adj plating or electroplat\$3	USPAT;	2003/07/11
		near5 anneal\$3 and electrolytic or	US-PGPUB;	17:51
		chemical adj polishing) and substrate	EPO; JPO;	
216	1044	((copper adj plating or electroplat\$3	DERWENT USPAT:	2002/07/11
210	1044	near5 anneal\$3 and electrolytic or	US-PGPUB;	2003/07/11 17:52
		chemical adj polishing) and substrate)	EPO; JPO;	
222	140	and interconnect	DERWENT	
222	140	<pre>(((copper adj plating or electroplat\$3 near5 anneal\$3 and electrolytic or</pre>	USPAT;	2003/07/11
·		chemical adj polishing) and substrate)	US-PGPUB; EPO; JPO;	18:21
		and interconnect) and housing	DERWENT	
228	171444	anneal\$3	USPAT;	2003/07/11
			US-PGPUB;	18:22
	•	•	EPO; JPO; DERWENT	
234	11648	copper adj plating	USPAT;	2003/07/11
			US-PGPUB;	18:22
	,		EPO; JPO;	
240	89364	electrochemical or chemical adj polish\$3	DERWENT USPAT;	2003/07/11
ĺ		and the second of the second o	US-PGPUB;	18:24
	İ		EPO; JPO;	
246	116	anneals? AND /genner add blatter) are	DERWENT	0002/07/11
230	110	anneal\$3 AND (copper adj plating) AND (electrochemical or chemical adj	USPAT; US-PGPUB;	2003/07/11 18:51
[polish\$3)	EPO; JPO;	10.01
	_		DERWENT	<u> </u>
252	8	annealing same copper adj plating same	USPAT;	2003/07/11
ļ		polishing	US-PGPUB; EPO; JPO;	18:56
.			DERWENT	
258	4	annealing same copper adj electroplating	USPAT;	2003/07/11
ļ	.	same polishing	US-PGPUB;	18:56
İ			EPO; JPO;	
L	l		DERWENT	

	-	275	205/223.ccls.	USPAT;	2003/07/11
				US-PGPUB;	16:45
				EPO; JPO;	
	_	15	205/223.ccls. and interconnect	DERWENT	1
		1	2007225.CCIS. and Interconnect	USPAT;	2003/05/13
		İ		US-PGPUB;	18:16
				EPO; JPO;	
.	_	14	205/223.ccls. and interconnect and etch\$3	DERWENT USPAT;	2003/05/13
			y === === and indepointed diffe eccitys	US-PGPUB;	18:16
- 1				EPO; JPO;	10.10
			·	DERWENT	1
	-	222	anneal\$3 adj section	USPAT;	2003/07/11
			'	US-PGPUB;	15:46
			•	EPO; JPO;	Ì
İ	_	1 0	anneal\$3 adj section SAME	DERWENT	
		Ĭ	electropolish\$3	USPAT;	2003/07/11
- 1			diccelopolismos	US-PGPUB;	15:41
-				EPO; JPO; DERWENT	.
1	-	0	anneal\$3 adj section SAME chemical adj	USPAT;	2003/07/11
- [polish	US-PGPUB;	15:41
				EPO; JPO;	10111
				DERWENT	
	-	1	anneal\$3 adj section SAME chemical adj	USPAT;	2003/07/11
			polish\$3	US-PGPUB;	15:41
				EPO; JPO;	
1	_	165	anneal\$3 adj area	DERWENT	
1		100	annearys adj area	USPAT;	2003/07/11
				US-PGPUB;	15:45
				EPO; JPO; DERWENT	i
	-	6	(anneal\$3 adj area) AND (anneal\$3 adj	USPAT;	2003/07/11
			section)	US-PGPUB;	15:43
1			•	EPO; JPO;	1201.10
İ	-	_		DERWENT	1
1	_	1		USPAT;	2003/07/11
			polish\$3	US-PGPUB;	15:45
				EPO; JPO;	
	_) o	anneal\$3 adj area SAME electropolish\$3	DERWENT	0000 (00 (00
			ammonths and alea parts electiobolisus?	USPAT; US-PGPUB;	2003/07/11 15:46
			, '	EPO; JPO;	15:46
İ			-	DERWENT	
	-	4637	anneal\$3 SAME polish\$3	USPAT;	2003/07/11
				US-PGPUB;	15:48
]		EPO; JPO;	
1.	-	1024	/anno-102 garge 1/ 1/2	DERWENT	
Γ		1924	(anneal\$3 SAME polish\$3) and electro\$10	USPAT;	2003/07/11
		[]	,	US-PGPUB;	15:48
] !		EPO; JPO;	1
-		16	anneal\$3 SAME electropolish\$3 SAME	DERWENT USPAT;	2003/07/11
	*		chemical	US-PGPUB;	15:52
				EPO; JPO;	10.02
		,		DERWENT	
-	=	1956	anneal\$3 AND 204/\$.ccls.	USPAT;	2003/07/11
İ				US-PGPUB;	15:53
1			.]	EPO; JPO;	
۱ -	-	38	anneal\$3 AND 204/\$.ccls. AND	DERWENT	0000/07/65
		1 30	electropolish\$3	USPAT;	2003/07/11
				US-PGPUB; EPO; JPO;	16:20
		,	·	DERWENT	
-	-	. 55192	(anneal\$3 AND 204/\$.ccls. AND	USPAT;	2003/07/11
		[electropolish\$3) AND copper NEAR plat\$3	US-PGPUB;	16:13
		j ł	or electroplat\$3	EPO; JPO;	
_		25	(ama-162 ava con/4 -	DERWENT	
] 43	(anneal\$3 AND 204/\$.ccls. AND	USPAT;	2003/07/11
		[electropolish\$3) AND copper	US-PGPUB;	16:13
				EPO; JPO;	
=				DERWENT	

<u>-</u>	786	anneal\$3	AND	chemical	NEAR	polish\$3	USPAT;	2003/07/11
						-	US-PGPUB;	16:24
		•					EPO; JPO;	
							DERWENT	
-	0	anneal\$3	AND	electroher	nical	NEAR	USPAT;	2003/07/11
		polish\$3					US-PGPUB;	16:23
				•			EPO; JPO;	
					_		DERWENT	0000/07/11
-	55203	(anneal\$3	AND			R polish\$3)	USPAT;	2003/07/11
		and copper	adj	plat\$3 or (electi	coplat\$3	US-PGPUB;	16:28
							EPO; JPO;	
							DERWENT	2003/07/11
-	23	(anneal\$3	AND		NEAL	R polish\$3)	USPAT;	16:49
		and copper	adj	prat\$3		•	US-PGPUB; EPO; JPO;	10.49
	1						DERWENT	
		L					DEKARMI	